

HMC334LP4 / 334LP4E

v03.0410



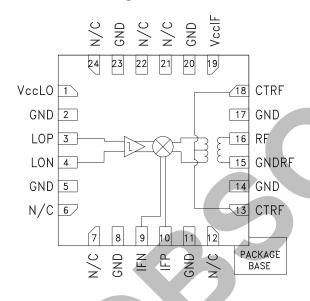
SiGe WIDEBAND DOWNCONVERTER, 0.6 - 2.7 GHz

Typical Applications

The HM334LP4(E) is ideal for:

- Basestations & Repeaters
- GSM, GPRS & Edge
- CDMA, W-CDMA & TD-SCDMA
- WiMAX & LTE

Functional Diagram



Features

Conversion Loss: 0 dB LO to RF Isolation: 48 dB

Single-Ended LO Drive: -6 to +6 dBm

Input IP3: +26 dBm

SSB Noise Figure: 11 dB

On-Chip RF Balun

24 Lead 4x4mm QFN Package: 16 mm²

General Description

The HMC334LP4(E) is a low noise, wideband downconverter RFIC which is ideal for Cellular/3G and WiMAX/4G applications from 0.6 to 2.7 GHz. The LO input accepts drive levels from -6 to +6 dBm while the RFIC provides 48 dB of LO to RF isolation, and 0 dB conversion loss. The HMC334LP4(E) will support an IF output bandwidth of up to 600 MHz and consumes only 173 mA from a +5V supply. This wideband active mixer also provides excellent performance in the presence of high level "Blocker" signals, making it ideal for receiver applications in demanding environments.

Electrical Specifications,

 $T_A = +25 \, ^{\circ}\text{C}$, LO = 0 dBm*, Vslo = VsiF = +5V, IF = 240 MHz

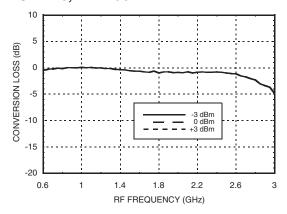
| Parameter | Min. | Тур. | Max. | Units |
|------------------------------------|----------------|------|------|-------|
| Frequency Range, RF | 0.6 - 2.7 | | GHz | |
| Frequency Range, LO | 0.35 - 3.0 GHz | | GHz | |
| Frequency Range, IF | 1 - 600 | | | MHz |
| Conversion Gain (IF XFMR Included) | -5 | -1 | | dB |
| SSB Noise Figure | | 11 | | dB |
| LO to RF Isolation | 30 | 48 | | dB |
| IF Output Impedance (Diff) | | 200 | | Ohms |
| IP3 (Input) | | +26 | | dBm |
| 1 dB Compression (Input) | | 12 | | dBm |
| LO Drive Input Level | -6 to +6 dBm | | dBm | |
| Supply Current | | 173 | 225 | mA |

^{*}Unless otherwise noted all measurements with R1 = 13 Ohms and single-ended 50 Ohm IF output with Port J2 or J3 shorted to ground.

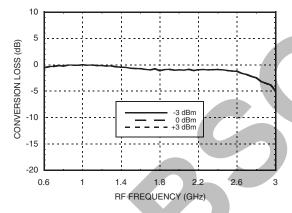




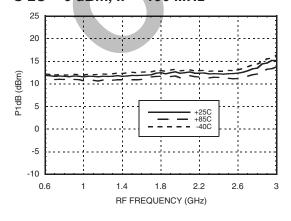
Conversion Gain vs. LO Drive, IF = 100 MHz [1]



Conversion Gain vs. LO Drive, IF = 240 MHz [1]

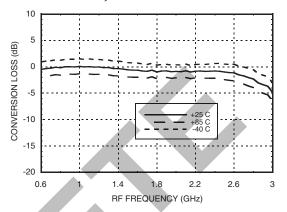


P1dB vs. Temperature @ LO = 0 dBm, IF = 100 MHz [1]

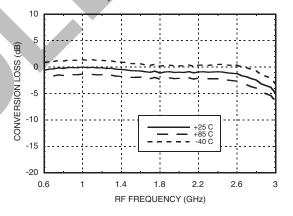


SiGe WIDEBAND **DOWNCONVERTER**, 0.6 - 2.7 GHz

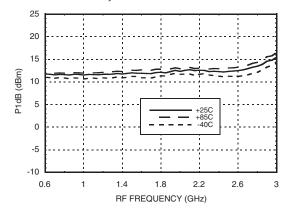
Conversion Gain vs. Temperature @ LO = 0 dBm, IF = 100 MHz [1]



Conversion Gain vs. Temperature @ LO = 0 dBm, IF = 240 MHz [1]



P1dB vs. Temperature @ LO = 0 dBm, IF = 240 MHz [1]



[1] LO < RF

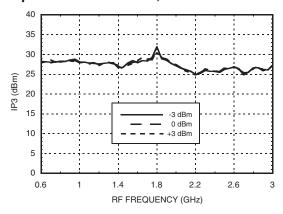
^{*} Unless otherwise noted all measurements with R1= 13 Ohms



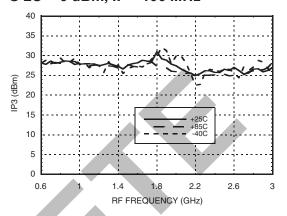


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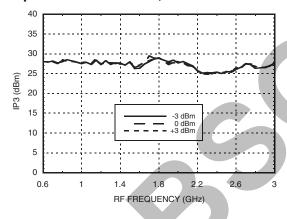
Input IP3 vs. LO Drive, IF = 100 MHz [1]



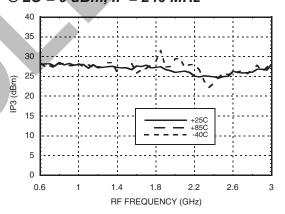
Input IP3 vs. Temperature @ LO = 0 dBm, IF = 100 MHz [1]



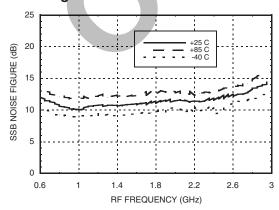
Input IP3 vs. LO Drive, IF = 240 MHz [1]



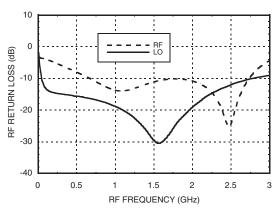
Input IP3 vs. Temperature @ LO = 0 dBm, IF = 240 MHz [1]



Noise Figure [1]



RF Return Loss @ LO = 0 dBm [1]



[1] LO < RF * Unless otherwise noted all measurements with R1= 13 Ohms

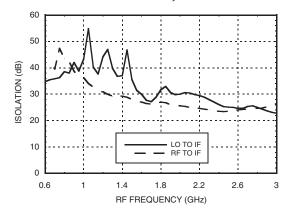
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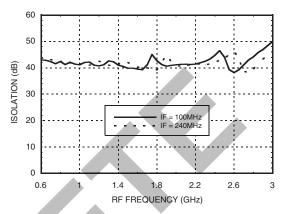


SiGe WIDEBAND DOWNCONVERTER, 0.6 - 2.7 GHz

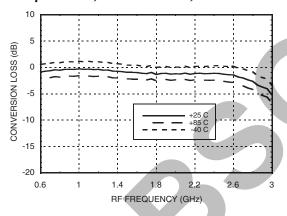
Isolation @ LO = 0 dBm, IF = 100 MHz [1]



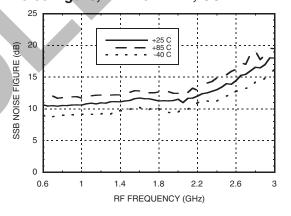
LO - RF Isolation @ LO = 0 dBm [1]



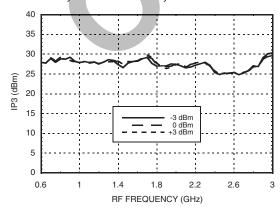
Conversion Gain vs.
Temperature, IF = 184 MHz, USB [2]



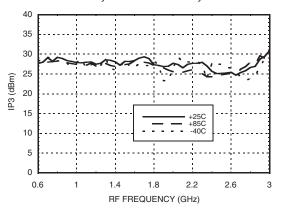
Noise Figure, IF = 184 MHz, USB [2]



Input IP3 vs. LO Drive, IF = 184 MHz, USB [2]



Input IP3 vs. Temperature @ LO = 0 dBm, IF = 184 MHz, USB [2]



[1] LO < RF [2] LO > RF





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Absolute Maximum Ratings

| RF Input (VsLo = VsIF= +5V) | +21 dBm |
|---|---------------|
| LO Drive (VsLo = VsIF= +5V) | +12 dBm |
| VccLO, VccIF | +6 Vdc |
| Channel Temperature | 150 °C |
| Continuous Pdiss (T = 85°C) (derate 27.8 mW/°C above 85°C) | 1.8 W |
| Thermal Resistance (channel to ground paddle) | 36 °C/W |
| Storage Temperature | -65 to 150 °C |
| Operating Temperature | -40 to 85 °C |

Typical Supply Current vs. Supply Voltage

| VsLo = VsIF (V) | Islo + IsiF (mA) | |
|---|------------------|--|
| +4.5 | 146 | |
| +5.0 | 173 | |
| +5.5 | 200 | |
| Downconverter will operate over full voltage range shown above. | | |



Outline Drawing

BOTTOM VIEW .161 4.10 .153 3.90 -.016 [0.40] REF .012 \[0.30 \] .007 \[0.18 \] .008 [0.20] MIN 19 PIN 1 HNNN XXXX 6 **EXPOSED** LOT NUMBER **GROUND PADDLE** 1.00 0.80 **SQUARE** 0.05 NOTES: SEATING 1. LEADFRAME MATERIAL: COPPER ALLOY PLANE 2. DIMENSIONS ARE IN INCHES [MILLIMETERS] △ .003[0.08] C 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE. -c-

- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [3] |
|-------------|--|---------------|------------|---------------------|
| HMC334LP4 | Low Stress Injection Molded Plastic | Sn/Pb Solder | MSL1 [1] | H334 XXXX |
| HMC334LP4E | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [2] | H334 XXXX |

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX





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Pin Descriptions

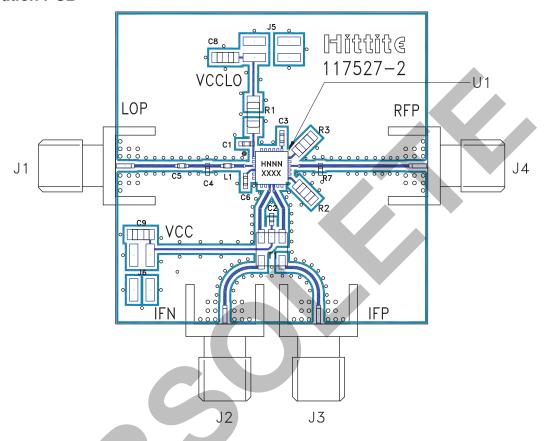
| Pin Number | Function | Description | Interface Schematic |
|--------------------------------|----------|---|-----------------------|
| 1 | VccLO | Supply for LO Amplifier. Draws approximately 120mA from VSLO. A 13 Ohm resistor (R1) must be connected externally between the VSLO supply and the VccLO pin. See evaluation PCB schematic. | VecLO O LO DRIVE |
| 2, 5, 8, 11, 14, 17, 20, 23 | GND | These pins and the ground paddle should be connected to a high quality RF/DC ground. | GND |
| 3 | LOP | LO Input Port. This pin needs a DC blocking capacitor. (Typical voltage on this pin will be 1.5 - 1.8V) | VccL0 ○ |
| 4 | LON | For single ended applications, this pin should be AC grounded | LON O |
| 6, 7, 12, 21, 22, 24 | N/C | The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally. | |
| 9, 10 | IFN, IFP | Differential baseband outputs, 200 ohm differential output impedance. Each port should draw approximately 25mA from VSIF without LO power and 28mA from VSIF with LO power on. For single-ended 50 Ohm operation, port J2 or J3 should be shorted to RF/DC ground. See evaluation PCB schematic. | VecilF VecilF O IFP |
| 13, 18 | CTRF | Center tap of the RF transformer. Biased at 2.2V when connected to ground through two 91 ohm resistors. | - OCTRF |
| 15 | GNDRF | Pin to be connected to a high quality RF/DC ground. Also can be used to drive the RF port differentially if needed. | 3 E |
| 16 | RF | 50 Ohms impedance can be matched from 600 - 3000 MHz. | 3 |
| 19 | VccIF | Supply decoupling for the mixer stage. (Typical voltage on this pin will be 4.8V) Connect C3 to a high quality RF/DC ground per evaluation PCB schematic. | VccIF O MIXER |





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Evaluation PCB



List of Materials for Evaluation PCB 117528 [1]

| Item | Description |
|---------|---------------------------------|
| J1 - J4 | Johnson SMA Connector |
| J5 - J6 | 2mm SMT |
| C1 - C3 | 1000 pF Capacitor, 0402 Pkg. |
| C4 | 0.3 pF Capacitor, 0402 Pkg. |
| C5 | 100 pF Capacitor, 0402 Pkg. |
| C6 | 10 KpF Capacitor, 0402 Pkg. |
| C7 | 1.3 pF Capacitor, 0402 Pkg. |
| C8, C9 | 0.1 μF Capacitor, 0805 Pkg. |
| L1 | 2.7 nH Chip Inductor, 0603 Pkg. |
| L2 | 2 nH Chip Inductor, 0603 Pkg. |
| R1 | 13 Ohm Resistor, 1206 Pkg. |
| R2, R3 | 91 Ohm Resistor, 0805 Pkg. |
| T1 | M/A-Com 4:1 Balun, MABAES0061 |
| U1 | HMC334LP4 / HMC334LP4E |
| PCB [2] | 117527 Evaluation Board |

[1] Reference this number when ordering complete evaluation PCB [2] Circuit Board Material: Rogers 4350

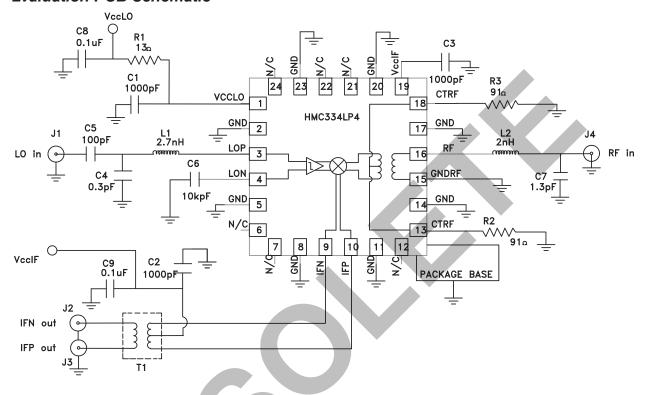
The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



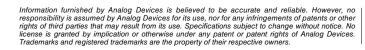


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Evaluation PCB Schematic



Note: For single-ended 50 Ohms operation, port J2 or J3 should be shorted to RF/DC ground.



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